

0590B

ceramic dual in-line package (600 mil); 40 leads; F: no window; FA: with window

10 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	CDIP40
Package style descriptive code	CDIP (ceramic dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	C (ceramic)
Mounting method type	T (through-hole mount)
Issue date	17-1-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
n ₂	actual quantity of termination	-	-	40	-	



2. Package outline

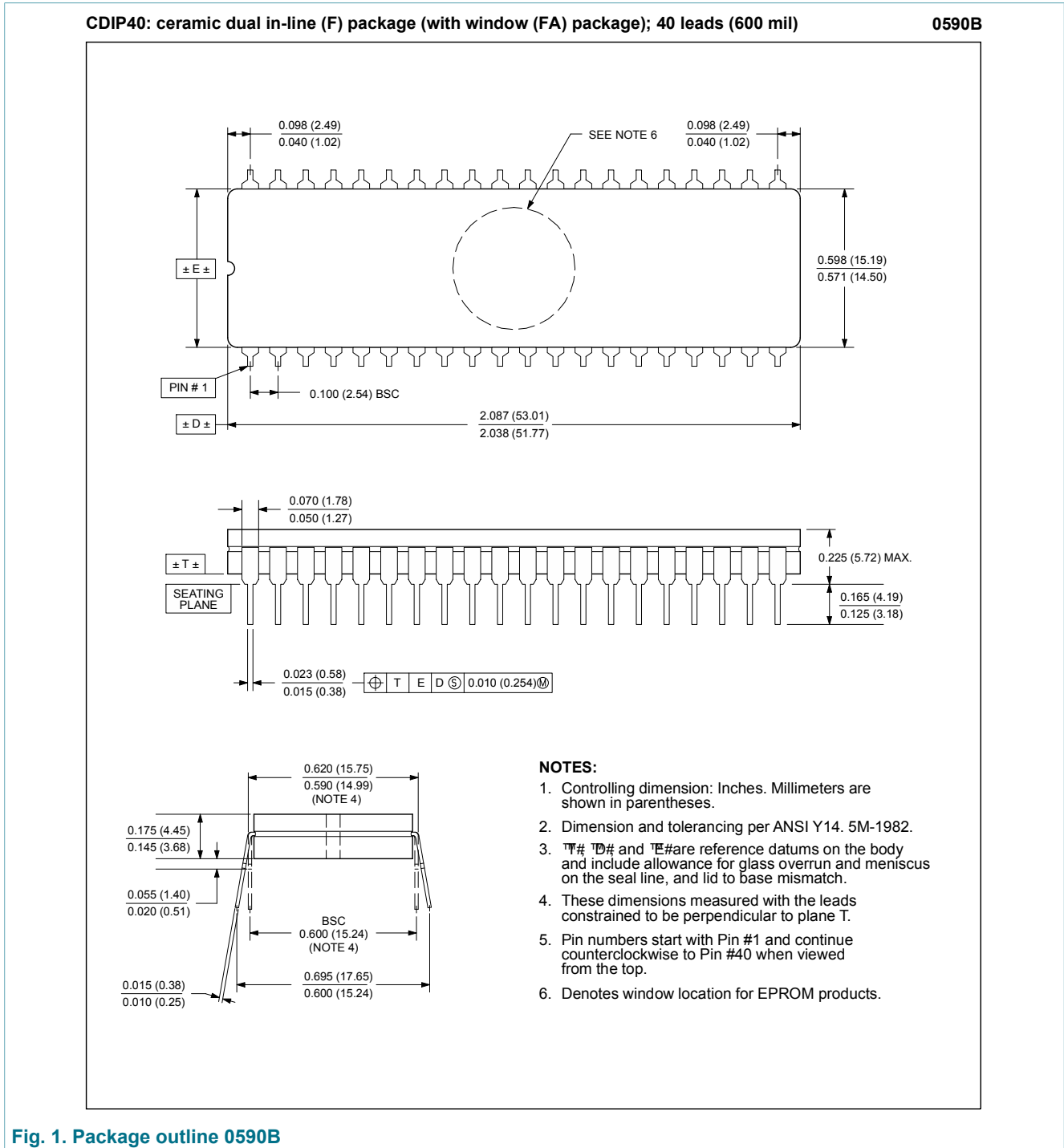


Fig. 1. Package outline 0590B

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3. Legal information

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